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October 1997 Revised June 2005

74VCX16374

Low Voltage 16-Bit D-Type Flip-Flops with 3.6V Tolerant Inputs and Outputs

General Description

The VCX16374 contains sixteen non-inverting D-type flipflops with 3-STATE outputs and is intended for bus oriented applications. The device is byte controlled. A buffered clock (CP) and output enable $(\overline{\text{OE}})$ are common to each byte and can be shorted together for full 16-bit operation.

The 74VCX16374 is designed for low voltage (1.2V to 3.6V) $\rm V_{CC}$ applications with I/O compatibility up to 3.6V.

The 74VCX16374 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining low CMOS power dissipation.

Features

- 1.2V to 3.6V V_{CC} supply operation
- 3.6V tolerant inputs and outputs
- t_{DD}

3.0 ns max for 3.0V to 3.6V V_{CC}

- Power-off high impedance inputs and outputs
- Supports live insertion and withdrawal (Note 1)
- Static Drive (I_{OH}/I_{OL})
 - ±24 mA @ 3.0V V_{CC}
- Uses proprietary noise/EMI reduction circuitry
- Latch-up performance exceeds 300 mA
- ESD performance:

Human body model > 2000V

Machine model > 200V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

Note 1: To ensure the high-impedance state during power up or power down, $\overline{\text{DE}}$ should be tied to V_{CC} through a pull-up resistor; the minimum value of the resistor is determined by the current-sourcing capability of the driver.

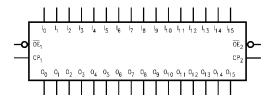
Ordering Code:

Order Number	Package Number	Package Descriptions
74VCX16374G (Note 2)(Note 3)	BGA54A	54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide
74VCX16374MTD (Note 3)	MTD48	48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide

Note 2: Ordering code "G" indicates Trays.

Note 3: Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbol

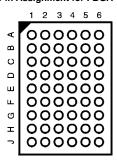


Connection Diagrams

Pin Assignment for TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

Pin Names	Description
OE _n	Output Enable Input (Active LOW)
CP _n	Clock Pulse Input
I ₀ -I ₁₅	Inputs
O ₀ -O ₁₅	Outputs
NC	No Connect

FBGA Pin Assignments

	1	2	3	4	5	6
Α	O ₀	NC	OE ₁	CP ₁	NC	I ₀
В	02	O ₁	NC	NC	I ₁	l ₂
С	O ₄	Ο ₃	V _{CC}	V _{CC}	I ₃	I ₄
D	O ₆	O ₅	GND	GND	I ₅	I ₆
Е	O ₈	07	GND	GND	l ₇	I ₈
F	O ₁₀	O ₉	GND	GND	l ₉	I ₁₀
G	O ₁₂	O ₁₁	V _{CC}	V _{CC}	I ₁₁	I ₁₂
Н	O ₁₄	O ₁₃	NC	NC	I ₁₃	I ₁₄
J	O ₁₅	NC	OE ₂	CP ₂	NC	I ₁₅

Truth Tables

	Inputs		Outputs
CP ₁	OE ₁	I ₀ –I ₇	0 ₀ –0 ₇
~	L	Н	Н
~	L	L	L
L	L	Χ	O ₀
Х	Н	Χ	Z

	Inputs		Outputs
CP ₂	OE ₂	I ₈ -I ₁₅	O ₈ -O ₁₅
~	L	Н	Н
~	L	L	L
L	L	Х	O_0
Х	Н	Χ	Z

H = HIGH Voltage Level
L = LOW Voltage Level

X = Immaterial (HIGH or LOW, inputs may not float)
Z = High Impedance

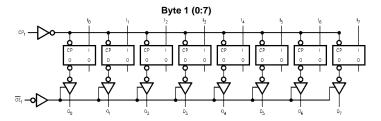
 $O_0 = Previous O_0$ before HIGH-to-LOW of CP

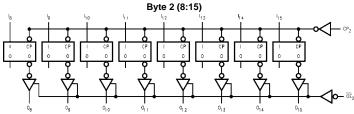
Functional Description

The 74VCX16374 consists of sixteen edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The device is byte controlled with each byte functioning identically, but independent of the other. The control pins can be shorted together to obtain full 16-bit operation. Each clock has a buffered clock and buffered Output Enable common to all flip-flops within that byte. The description which follows applies to each byte. Each

flip-flop will store the state of their individual I inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP_n) transition. With the Output Enable (\overline{OE}_n) LOW, the contents of the flip-flops are available at the outputs. When \overline{OE}_n is HIGH, the outputs go to the high impedance state. Operations of the \overline{OE}_n input does not affect the state of the flip-flops.

Logic Diagram





Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings(Note 4)

 $\begin{array}{lll} \mbox{Supply Voltage (V$_{CC}$)} & -0.5 \mbox{V to } +4.6 \mbox{V} \\ \mbox{DC Input Voltage (V$_{O}$)} & -0.5 \mbox{V to } +4.6 \mbox{V} \\ \mbox{Output Voltage (V$_{O}$)} & \end{array}$

Outputs 3-STATED -0.5 V to +4.6 VOutputs Active (Note 5) $-0.5 \text{V to } \text{V}_{\text{CC}} +0.5 \text{V}$

DC Input Diode Current (I_{IK}) $V_I < 0V$ —50 mA

DC Output Diode Current (I_{OK})

 V_{O} < 0V -50 mA V_{O} > V_{CC} +50 mA

DC Output Source/Sink Current

 (I_{OH}/I_{OL}) ±50 mA

DC V_{CC} or GND Current per

Supply Pin (I_{CC} or GND) ± 100 mA

Storage Temperature Range (T_{STG}) $-65^{\circ}C$ to $+150^{\circ}C$

Recommended Operating Conditions (Note 6)

Power Supply

Operating 1.2V to 3.6V Input Voltage -0.3V to +3.6V

Output Voltage (V_O)

Output in Active States 0V to V_{CC} Output in "OFF" State 0.0V to 3.6V

Output Current in I_{OH}/I_{OL}

 $V_{CC} = 3.0 \text{V to } 3.6 \text{V}$ ±24 mA

 $\begin{array}{lll} \mbox{V}_{CC} = 2.3 \mbox{V to } 2.7 \mbox{V} & \pm 18 \mbox{ mA} \\ \mbox{V}_{CC} = 1.65 \mbox{V to } 2.3 \mbox{V} & \pm 6 \mbox{ mA} \\ \mbox{V}_{CC} = 1.4 \mbox{V to } 1.6 \mbox{V} & \pm 2 \mbox{ mA} \\ \end{array}$

 $V_{CC} = 1.2V \\ \mbox{Free Air Operating Temperature (T_A)} \\ \mbox{-40°C to $+85^{\circ}$C}$

Minimum Input Edge Rate (Δt/ΔV)

 $V_{IN} = 0.8V$ to 2.0V, $V_{CC} = 3.0V$ 10 ns/V

Note 4: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 5: I_O Absolute Maximum Rating must be observed.

Note 6: Floating or unused inputs must be held HIGH or LOW.

DC Electrical Characteristics

Symbol	Parameter	Conditions	V _{CC}	Min	Max	Units
			(V)			
V _{IH}	HIGH Level Input Voltage		2.7 - 3.6	2.0		
			2.3 - 2.7	1.6		
			1.65 - 2.3	0.65 x V _{CC}		V
			1.4 - 1.6	0.65 x V _{CC}		
			1.2	0.65 x V _{CC}		
V _{IL}	LOW Level Input Voltage		2.7 - 3.6		0.8	
			2.3 - 2.7		0.7	
			1.65 - 2.3		0.35 x V _{CC}	V
			1.4 - 1.6		0.35 x V _{CC}	
			1.2		0.05 x V _{CC}	
V _{OH}	HIGH Level Output Voltage	I _{OH} = -100 μA	2.7 - 3.6	V _{CC} - 0.2		
		I _{OH} = -12 mA	2.7	2.2		
		$I_{OH} = -18 \text{ mA}$	3.0	2.4		
		I _{OH} = -24 mA	3.0	2.2		
		$I_{OH} = -100 \mu A$	2.3 - 2.7	V _{CC} - 0.2		
		$I_{OH} = -6 \text{ mA}$	2.3	2.0		
		I _{OH} = -12 mA	2.3	1.8		V
		I _{OH} = -18 mA	2.3	1.7		
		$I_{OH} = -100 \mu A$	1.65 - 2.3	V _{CC} - 0.2		
		I _{OH} = -6 mA	1.65	1.25		
		I _{OH} = -100 μA	1.4 - 1.6	V _{CC} - 0.2		
		I _{OH} = -2 mA	1.4	1.05		
		I _{OH} = -100 μA	1.2	V _{CC} - 0.2		

DC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{CC} (V)	Min	Max	Units
V _{OL}	LOW Level Output Voltage	I _{OL} = 100 μA	2.7 - 3.6		0.2	
		$I_{OL} = 12 \text{ mA}$	2.7		0.4	
		$I_{OL} = 18 \text{ mA}$	3.0		0.4	
		$I_{OL} = 24 \text{ mA}$	3.0		0.55	
		$I_{OL} = 100 \ \mu A$	2.3 - 2.7		0.2	
		I _{OL} = 12 mA	2.3		0.4	V
		$I_{OL} = 18 \text{ mA}$	2.3		0.6	V
		$I_{OL} = 100 \ \mu A$	1.65 - 2.3		0.2	
		$I_{OL} = 6 \text{ mA}$	1.65		0.3	
		$I_{OL} = 100 \ \mu A$	1.4 - 1.6		0.2	
		$I_{OL} = 2 \text{ mA}$	1.4		0.35	
		$I_{OL} = 100 \ \mu A$	1.2		0.05	
I	Input Leakage Current	$0 \leq V_I \leq 3.6V$	1.2 - 3.6		±5.0	μА
I _{OZ}	3-STATE Output Leakage	$0 \le V_O \le 3.6V$ $V_I = V_{IH} \text{ or } V_{IL}$	1.2 - 3.6		±10	μА
I _{OFF}	Power-OFF Leakage Current	$0 \leq (V_I, V_O) \leq 3.6V$	0		10	μА
I _{CC}	Quiescent Supply Current	V _I = V _{CC} or GND	1.2 - 3.6		20	μА
		$V_{CC} \le (V_I, V_O) \le 3.6V \text{ (Note 7)}$	1.2 - 3.6		±20	μΑ
Δl _{CC}	Increase in I _{CC} per Input	V _{IH} = V _{CC} -0.6V	2.7 - 3.6		750	μА

Note 7: Outputs disabled or 3-STATE only.

AC Electrical Characteristics (Note 8)

Symbol	Parameter	Conditions	V _{CC}	T _A = -40°C to +85°C		Units	Figure
- Cyllibol		Conditions	(V)	Min	Max	Oilles	Numbe
f _{MAX}	Maximum Clock Frequency	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	250			
			2.5 ± 0.2	200			Figures 1, 2
			1.8 ± 0.15	100		ns	1, 2
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	80			Figures
			1.2	40			7, 8
t _{PHL} ,	Propagation Delay CP to O _n	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.8	3.0		
t _{PLH}			2.5 ± 0.2	1.0	3.9		Figures 1, 2
			1.8 ± 0.15	1.5	7.8	ns	1, 2
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	15.6		Figures
			1.2	1.5	39		7, 8
t _{PZL} ,	Output Enable Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.8	3.5		1
t _{PZH}			2.5 ± 0.2	1.0	4.6		Figures 1, 3, 4
			1.8 ± 0.15	1.5	9.2	ns	1, 0, 1
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	18.4		Figures
			1.2	1.5	46		7, 9, 10
t _{PLZ} ,	Output Disable Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	0.8	3.5		
t _{PHZ}			2.5 ± 0.2	1.0	3.8		Figures 1, 3, 4
			1.8 ± 0.15	1.5	6.8	ns	1, 0, 4
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	1.0	13.6		Figures
			1.2	1.5	34		7, 9, 10
t _S	Setup Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	1.5			
			2.5 ± 0.2	1.5			Figures 1, 6
			1.8 ± 0.15	2.5		ns	., 0
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	3.0			Figures
			1.2	6			6, 7

AC Electrical Characteristics (Continued)

Symbol	Parameter	Conditions	V _{cc}	T _A = -40°	C to +85°C	Units	Figure
		Conditions	(V)	Min	Max		Number
t _H	Hold Time	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 1.0	1.0			
			2.5 ± 0.2	1.0			Figures 1, 6
			1.8 ± 0.15	1.0		ns	., 0
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	2.0			Figures
			1.2	6			6, 7
t _W	Pulse Width	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3	1.5			l
			2.5 ± 0.2	1.5			Figures 1, 4
			1.8 ± 0.15	4.0		ns	., .
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1	4.0			Figures
			1.2	8			4, 7
toshl	Output to Output Skew	$C_L = 30 \text{ pF}, R_L = 500\Omega$	3.3 ± 0.3		0.5		
toslh	(Note 9)		2.5 ± 0.2		0.5		
			1.8 ± 0.15		0.75	ns	
		$C_L = 15 \text{ pF}, R_L = 2k\Omega$	1.5 ± 0.1		1.5		
			1.2		1.2		

Note 8: For $C_L = 50_P F$, add approximately 300 ps to the AC maximum specification.

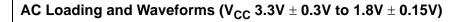
Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}).

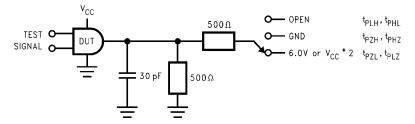
Dynamic Switching Characteristics

Symbol	Parameter	Conditions	v _{cc} (v)	T _A = +25°C	Units
V _{OLP}	Quiet Output Dynamic Peak V _{OL}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	0.25	
			2.5	0.6	V
			3.3	0.8	
V _{OLV}	Quiet Output Dynamic Valley V _{OL}	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	-0.25	
			2.5	-0.6	V
			3.3	-0.8	
V _{OHV}	Quiet Output Dynamic Valley VOH	$C_L = 30 \text{ pF}, V_{IH} = V_{CC}, V_{IL} = 0V$	1.8	1.5	
			2.5	1.9	V
			3.3	2.2	

Capacitance

Symbol	Parameter	Conditions	$T_A = +25$ °C	Units
- Cy20.	. a.aoro	o o na na na	Typical	J
C _{IN}	Input Capacitance	V_{CC} = 1.8V, 2.5V or 3.3V, V_I = 0V or V_{CC}	6	pF
C _{OUT}	Output Capacitance	V _I = 0V or V _{CC} , V _{CC} = 1.8V, 2.5V or 3.3V	7	pF
C _{PD}	Power Dissipation Capacitance	V _I = 0V or V _{CC} , f = 10 MHz, V _{CC} = 1.8V, 2.5V or 3.3V	20	pF
		V _{CC} = 1.8V, 2.5V or 3.3V	20	рі





TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	6V at V_{CC} = 3.3V \pm 0.3V; V_{CC} x 2V at V_{CC} = 2.5V \pm 0.2V; 1.8V \pm 0.15V
t_{PZH}, t_{PHZ}	GND

FIGURE 1. AC Test Circuit

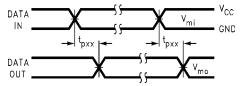


FIGURE 2. Waveform for Inverting and Non-Inverting Functions

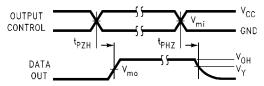


FIGURE 3. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

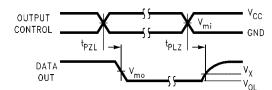


FIGURE 4. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

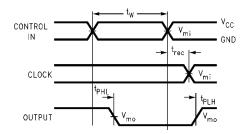


FIGURE 5. Propagation Delay, Pulse Width and $$t_{\rm rec}$$ Waveforms

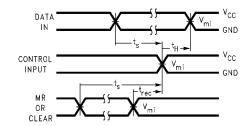
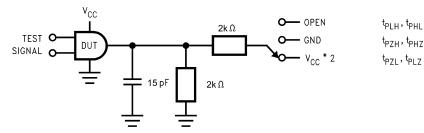


FIGURE 6. Setup Time, Hold Time and Recovery Time for Low Voltage Logic

Symbol	V _{CC}		
	3.3V ± 0.3V	2.5V ± 0.2V	1.8V ± 0.15V
V _{mi}	1.5V	V _{CC} /2	V _{CC} /2
V _{mo}	1.5V	V _{CC} /2	V _{CC} /2
V _X	V _{OL} + 0.3V	V _{OL} + 0.15V	V _{OL} + 0.15V
Vv	V _{ОН} – 0.3V	V _{ОН} – 0.15V	V _{OH} – 0.15V

AC Loading and Waveforms (V $_{ extsf{CC}}$ 0.15V \pm 0.1V to 1.2V)



TEST	SWITCH
t _{PLH} , t _{PHL}	Open
t _{PZL} , t _{PLZ}	V_{CC} x 2V at V_{CC} = 1.5V ± 0.1V
t _{PZH} , t _{PHZ}	GND

FIGURE 7. AC Test Circuit

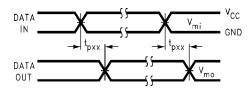


FIGURE 8. Waveform for Inverting and Non-Inverting Functions

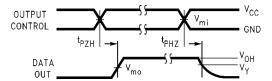


FIGURE 9. 3-STATE Output High Enable and Disable Times for Low Voltage Logic

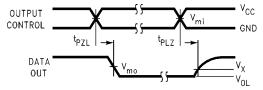
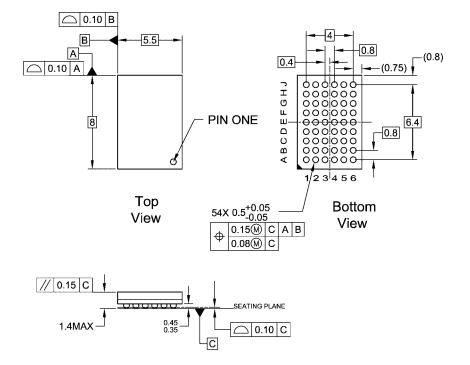


FIGURE 10. 3-STATE Output Low Enable and Disable Times for Low Voltage Logic

Symbol	v _{cc}	
Cymbo.	1.5V ± 0.1V	
V_{mi}	V _{CC} /2	
V_{mo}	V _{CC} /2	
V _X	V _{OL} + 0.1V	
V _Y	V _{OH} – 0.1V	

Physical Dimensions inches (millimeters) unless otherwise noted



NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- A. THIS PACKAGE CONFORMS TO JEDEC MI0-200

 B. ALL DIMENSIONS IN MILLIMETERS

 C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)

 .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS

 D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 ALL LEAD TIPS 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13\@ A B\S C\S 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Body Width Package Number MTD48

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